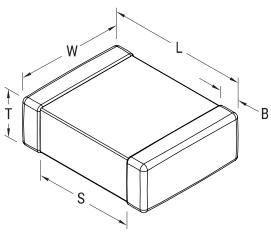




SMD Comm X8G HT150C Flex, Ceramic, 1,500 pF, 1%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.4 mm





S	AEC-Q200
	Typical Compo
Click here for the 3D model.	Shelf Life
	MSL
	MSL
Dimensions	MSL Specifications
Dimensions Chip Size 0603	
	Specifications
Chip Size 0603	Specification: Capacitance

0.4mm MIN

0.45mm +/-0.15mm

Packaging Specifications	
Packaging	T&R, 330mm, Paper Tape
Packaging Quantity	10000

S

В

General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	4.6 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	1,500 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	1%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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